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ABSTRACT

10 [PROBLEMS] To provide a polyimidesiloxane solution composition that is excellent in defoaming ability and that can maintain the wettability of an outer lead bonded portion on a wiring board at a high level, even when it is applied on the surface of the wiring board and then cured, to form an insulating cured film.

15 [MEANS FOR SOLVING PROBLEMS] A polyimidesiloxane solution composition which comprises an organic solvent, polyimidesiloxane soluble in the organic solvent, a curable components such as an epoxy compound and a polyvalent isocyanate compound, and a silicone defoamer, wherein the silicone defoaming agent comprises dimethylpolysiloxane, a polysiloxane compound having a hydrophilic group in a side chain or a terminal moiety, and a micro-
20 powder silica.